

3P Flip Chip

3-Pad InGaN LED Flip Chip

The best “performance / cost” ratio of InGAN LED Flip Chips

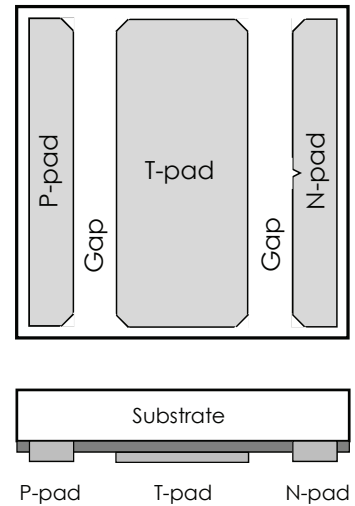
Brighter & Cooler

>30°C lower junction temperature / 20% increased Lumens

Flip Chip Opto’s patented “3-Pad” LED Flip Chip technology greatly increases the “performance / cost” ratio by offering a distinct advantage in thermal management, extending lumens output or operating temperature range by when integrated with our patented “MCPCB Pillar”.

Dimension:

Parameter	Type A	Type B
Chip Size:	1143µm x 1143µm	1125µm x 1125µm
Thickness:	150µm	250µm
P-pad & N-pad:	1059µm x 100µm	1045µm x 150µm
T-pad:	1059µm x 545µm	1045µm x 445µm
Gap:	150µm	150µm



Metallization: N-Pad, P-Pad and T-Pad: Ni/Au

Electro-Optical Characteristics:

Parameter	Symbol	Conditions	Ratings			Unit
			Min.	Typ.	Max.	
Dominant Wavelength	λ_D	If=700mA	448	455	462	nm
Radiant Power	PO		900		1020	mw
Forward Voltage	Vf				3.2	3.4
Reverse Current	Ir	Vr=-5V		1.0	2.0	µA

Maximum Ratings @ Ta=25°C

Parameter	Maximum Rating
LED Junction Temperature	145°C
DC Forward Current	1500mA
Reverse Voltage Vr	-5V @ Tambient = 25°C
Operating Case Temperature	-40°C to + 105°C
Storage Temperature	-40°C to + 120°C
Soldering Temperature	280C max for up to 3.5 seconds



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